



Description

The NTTFS5C471NL use advanced SGT MOSFET technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is specially designed to get better ruggedness and suitable.

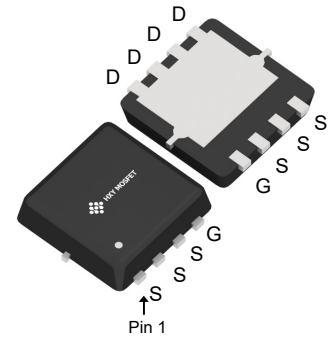
General Features

$V_{DS} = 40V$ $I_D = 40A$

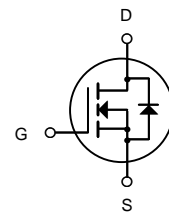
$R_{DS(ON)} < 8.5m\Omega @ V_{GS}=10V$

Applications

Consumer electronic power supply Motor control
Synchronous-rectification Isolated DC
Synchronous-rectification applications



DFN3X3-8L



N-Channel MOSFET

Ordering Information

| Product ID | Pack | Brand | Qty(PCS) |
|--------------|-----------|------------|----------|
| NTTFS5C471NL | DFN3X3-8L | HXY MOSFET | 5000 |

Absolute Maximum Ratings at $T_J=25^\circ C$ unless otherwise noted

| Parameter | Symbol | Value | Unit |
|--|---------------------|------------|--------------|
| Drain source voltage | V_{DS} | 40 | V |
| Gate source voltage | V_{GS} | ± 20 | V |
| Continuous drain current ¹⁾ | I_D | 40 | A |
| Pulsed drain current ²⁾ | I_D, pulse | 130 | A |
| Power dissipation ³⁾ | P_D | 39 | W |
| Single pulsed avalanche energy ⁵⁾ | EAS | 48 | mJ |
| Operation and storage temperature | T_{stg}, T_J | -55 to 150 | $^\circ C$ |
| Thermal resistance, junction-case | $R_{\theta JC}$ | 3.2 | $^\circ C/W$ |
| Thermal resistance, junction-ambient ⁴⁾ | $R_{\theta JA}$ | 60 | $^\circ C/W$ |



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|--|--|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =250uA | 40 | --- | --- | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =10V , I _D =12A | --- | 6.9 | 8.5 | mΩ |
| | | V _{GS} =4.5V , I _D =10A | --- | 10.0 | 15 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 1.35 | --- | 3 | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =32V , V _{GS} =0V , T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =32V , V _{GS} =0V , T _J =55°C | --- | --- | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V , V _{DS} =0V | --- | --- | ±100 | nA |
| R _g | Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | --- | 1.7 | --- | Ω |
| Q _g | Total Gate Charge (4.5V) | V _{DS} =20V , V _{GS} =4.5V , I _D =12A | --- | 5.8 | --- | nC |
| Q _{gs} | Gate-Source Charge | | --- | 3 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 1.2 | --- | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =15V , V _{GS} =10V , R _G =3.3Ω I _D =1A | --- | 14.3 | --- | ns |
| T _r | Rise Time | | --- | 5.6 | --- | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 20 | --- | |
| T _f | Fall Time | | --- | 11 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =15V , V _{GS} =0V , f=1MHz | --- | 690 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 193 | --- | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 38 | --- | |
| I _S | Continuous Source Current ^{1,5} | V _G =V _D =0V , Force Current | --- | --- | 40 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V , I _S =1A , T _J =25°C | --- | --- | 1 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=31A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

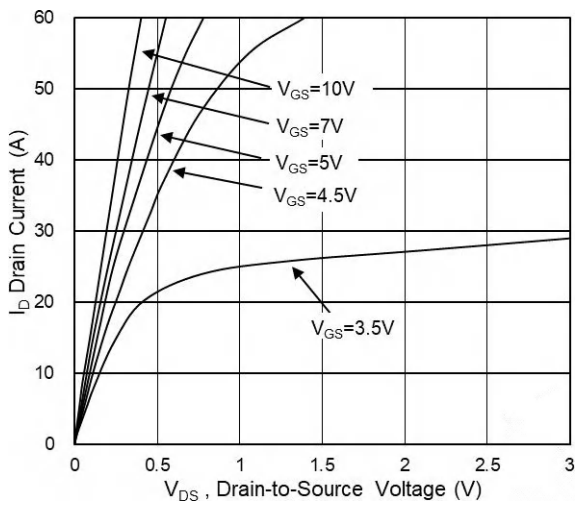


Fig.1 Typical Output Characteristics

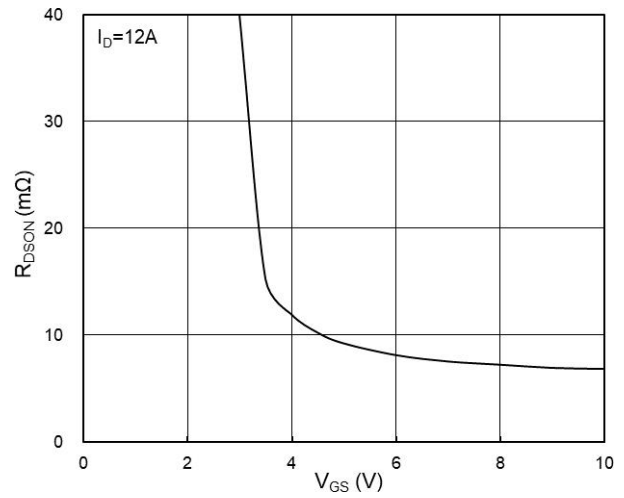


Fig.2 On-Resistance vs G-S Voltage

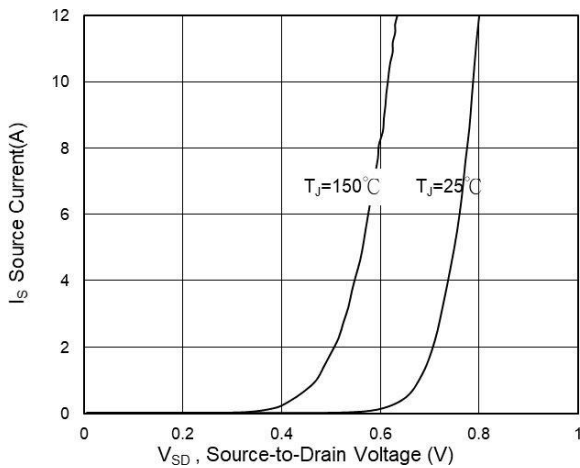


Fig.3 Source Drain Forward Characteristics

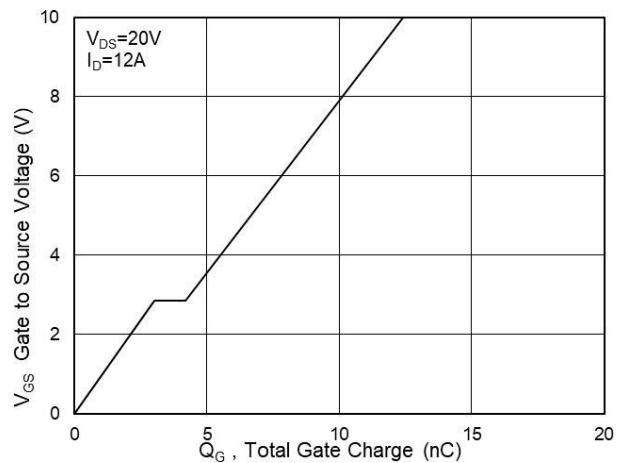


Fig.4 Gate-Charge Characteristics

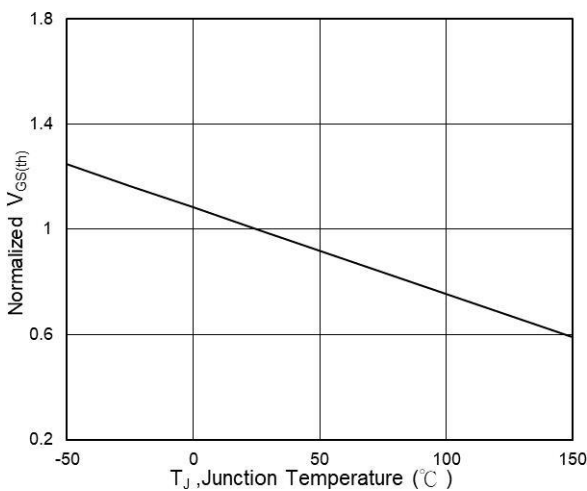


Fig.5 Normalized $V_{GS(th)}$ vs T_J

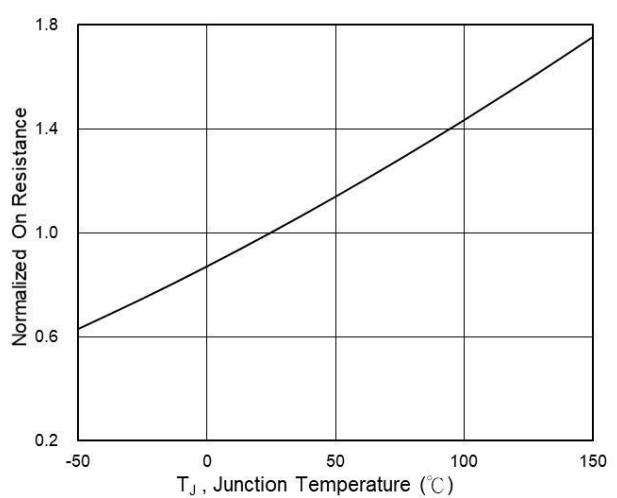


Fig.6 Normalized $R_{DS(on)}$ vs T_J

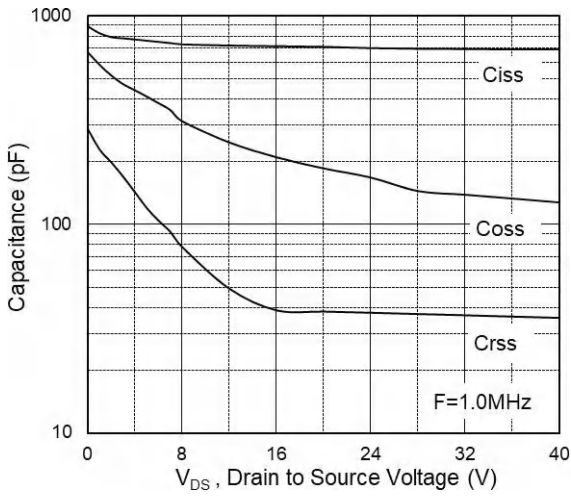


Fig.7 Capacitance

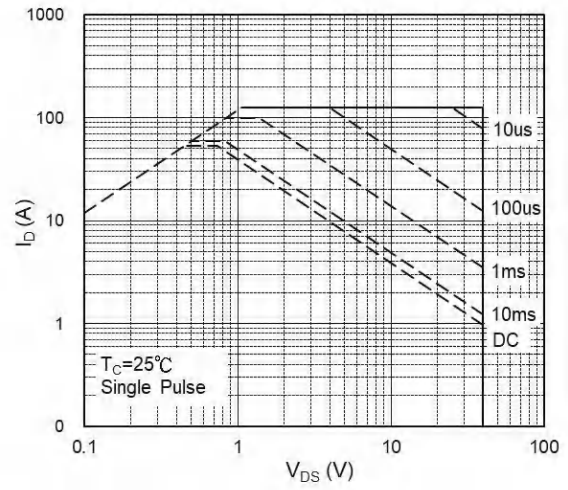


Fig.8 Safe Operating Area

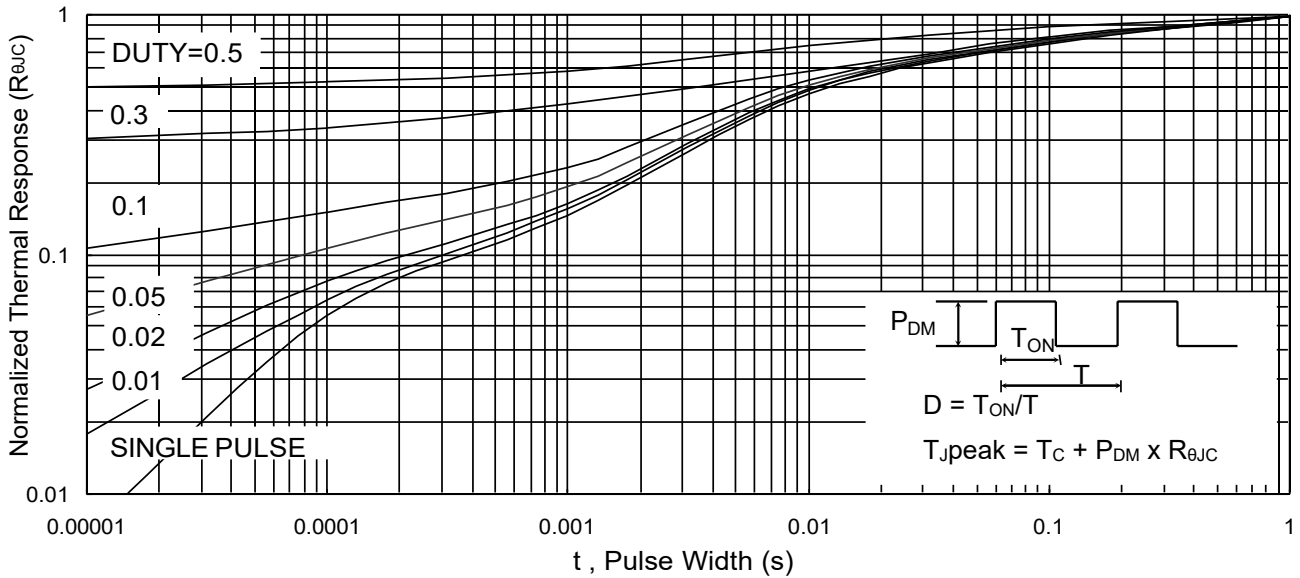


Fig.9 Normalized Maximum Transient Thermal Impedance

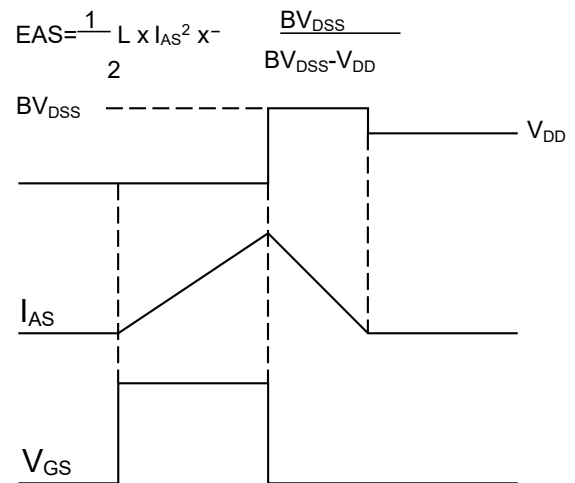
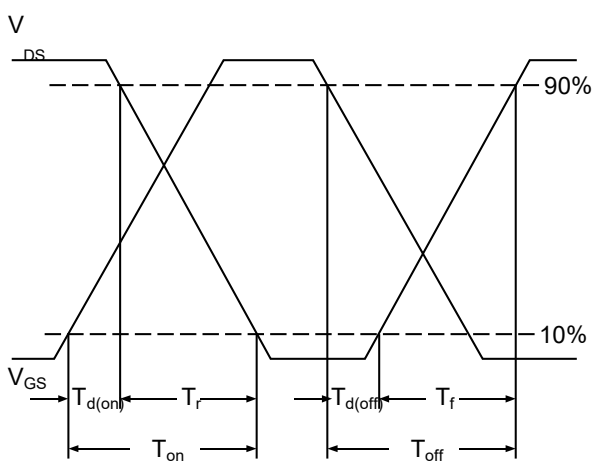
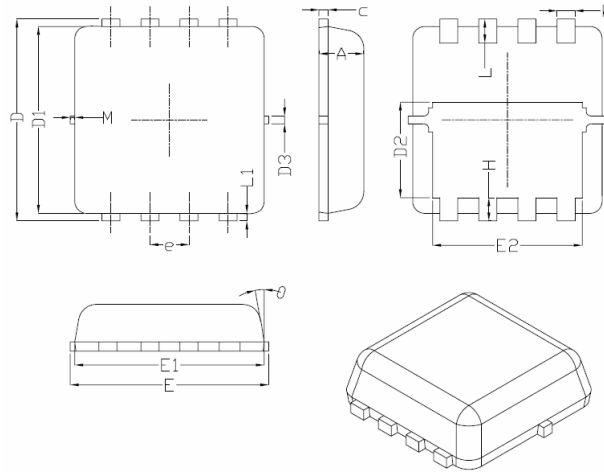


Fig.11 Unclamped Inductive Waveform



DFN3X3-8L Package Information



| Symbol | Dimensions In Millimeters | | |
|----------|---------------------------|------|------|
| | Min. | Nom. | Max. |
| A | 0.70 | 0.75 | 0.80 |
| b | 0.25 | 0.30 | 0.35 |
| c | 0.10 | 0.15 | 0.25 |
| D | 3.25 | 3.35 | 3.45 |
| D1 | 3.00 | 3.10 | 3.20 |
| D2 | 1.48 | 1.58 | 1.68 |
| D3 | - | 0.13 | - |
| E | 3.20 | 3.30 | 3.40 |
| E1 | 3.00 | 3.15 | 3.20 |
| E2 | 2.39 | 2.49 | 2.59 |
| e | 0.65BSC | | |
| H | 0.30 | 0.39 | 0.50 |
| L | 0.30 | 0.40 | 0.50 |
| L1 | - | 0.13 | - |
| M | * | * | 0.15 |
| θ | | 10° | 12° |



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